

Technical Notice

Issue Date: Nov. 25, 2016

Product Name: WAFER-BT-i1/ WAFER-BW

Implementation Date: Nov. 25

This notice is to inform you of changes to the WAFER-BT-i1 & WAFER-BW series.

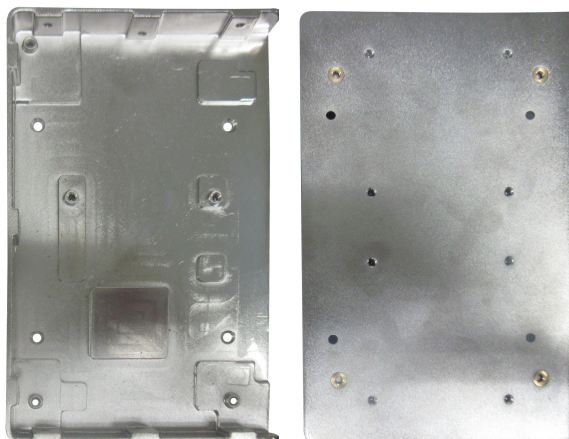
Reason for Change

Change heatsink vendor

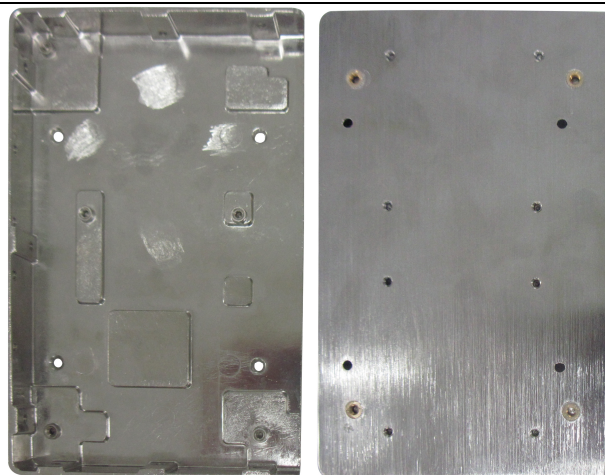
Description of Change.

Change heatsink vendor and the material surface from nickel plating with sandblasting to nickel plating with satin finish

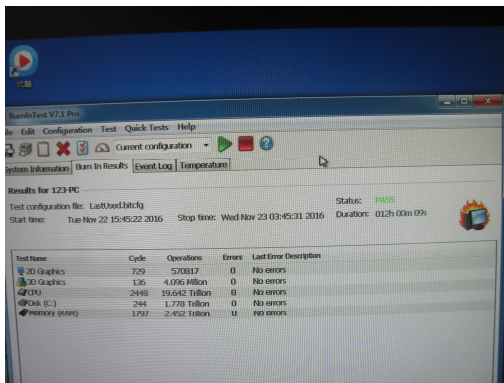
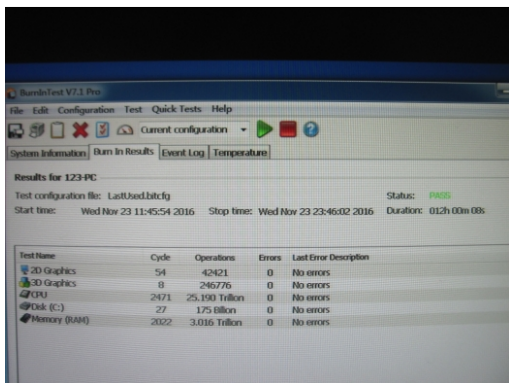
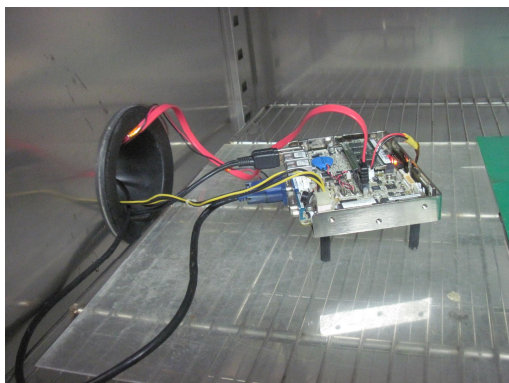
Original item



Substitute item



Burn In Test: PASS



| Temperature (°C) | Humidity (%) | Time (H) |
|------------------|--------------|----------|
| 65 | 95 | 12 |
| -20 | 0 | 12 |

Affected Model

Affected Model

WAFER-BT-i1-J19001-R10
 WAFER-BT-i1-N28071-R10
 WAFER-BT-i1-N29301-R10
 WAFER-BT-J19001-R10-ECO-R10
 WAFER-BW-N4-R10
 WAFER-BW-N3-R10
 WAFER-BW-N2-R10

Affected by This Change

- | | | | |
|---|-------------------------------------|--|----------------------------------|
| <input type="checkbox"/> Specifications | <input type="checkbox"/> Dimensions | <input checked="" type="checkbox"/> Appearance | <input type="checkbox"/> Package |
| <input type="checkbox"/> Certification | <input type="checkbox"/> Label | <input type="checkbox"/> BIOS | <input type="checkbox"/> Driver |

For more details please refer to the latest datasheet or visit <http://www.ieiworld.com>.

*Best Regards,
Elinor Chuang
Product Manager
IEI Integration Corp.*